

11-22-00  
FHY  
Breault D

Case No.: DENSE-015X

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: DENSE-PAC MICROSYSTEMS, INC. )  
Patent No.: 5,869,353 )  
Issued: FEBRUARY 9, 1999 )  
For: MODULAR PANEL STACKING PROCESS )

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D. C. 20231

Dear Sir/Madam:

Prior to the initial examination of the subject reissue patent application, please enter the following Preliminary Amendment.

IN THE CLAIMS:

Please add the following new claims into prosecution:

7. (New) A chip stack comprising:  
at least two packaged chips, each of the packaged chips having opposite sides and a  
multiplicity of leads extending from each of the opposite sides thereof; and  
at least one frame extending along at least each of the opposite sides of the packaged  
chips and comprising: